

Rev.E May.-2019

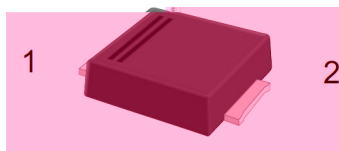
50V~600V 1.0A SMBF

Surface Mount Superfast Recovery Rectifier, Reverse Voltage: 50 to 600V, Forward Current: 1.0A, SMBF thin package.

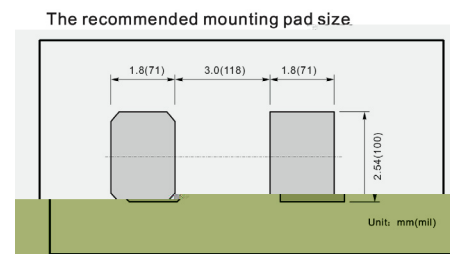
RoHS 2011/65/EU

Glass Passivated Chip Junction, Fast reverse recovery time, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

General purpose.



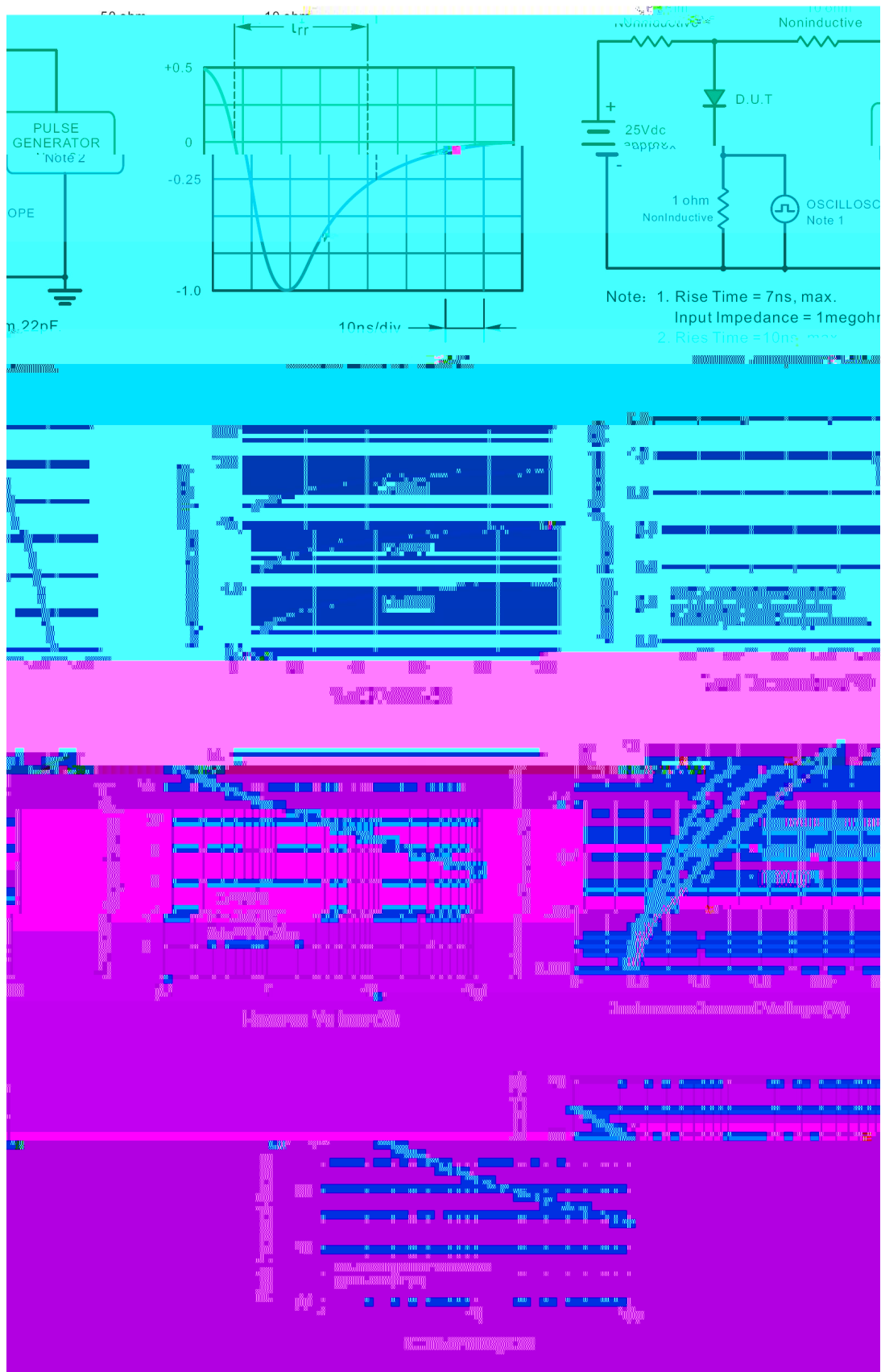
PIN	DESCRIPTION
1	Cathode
2	Anode



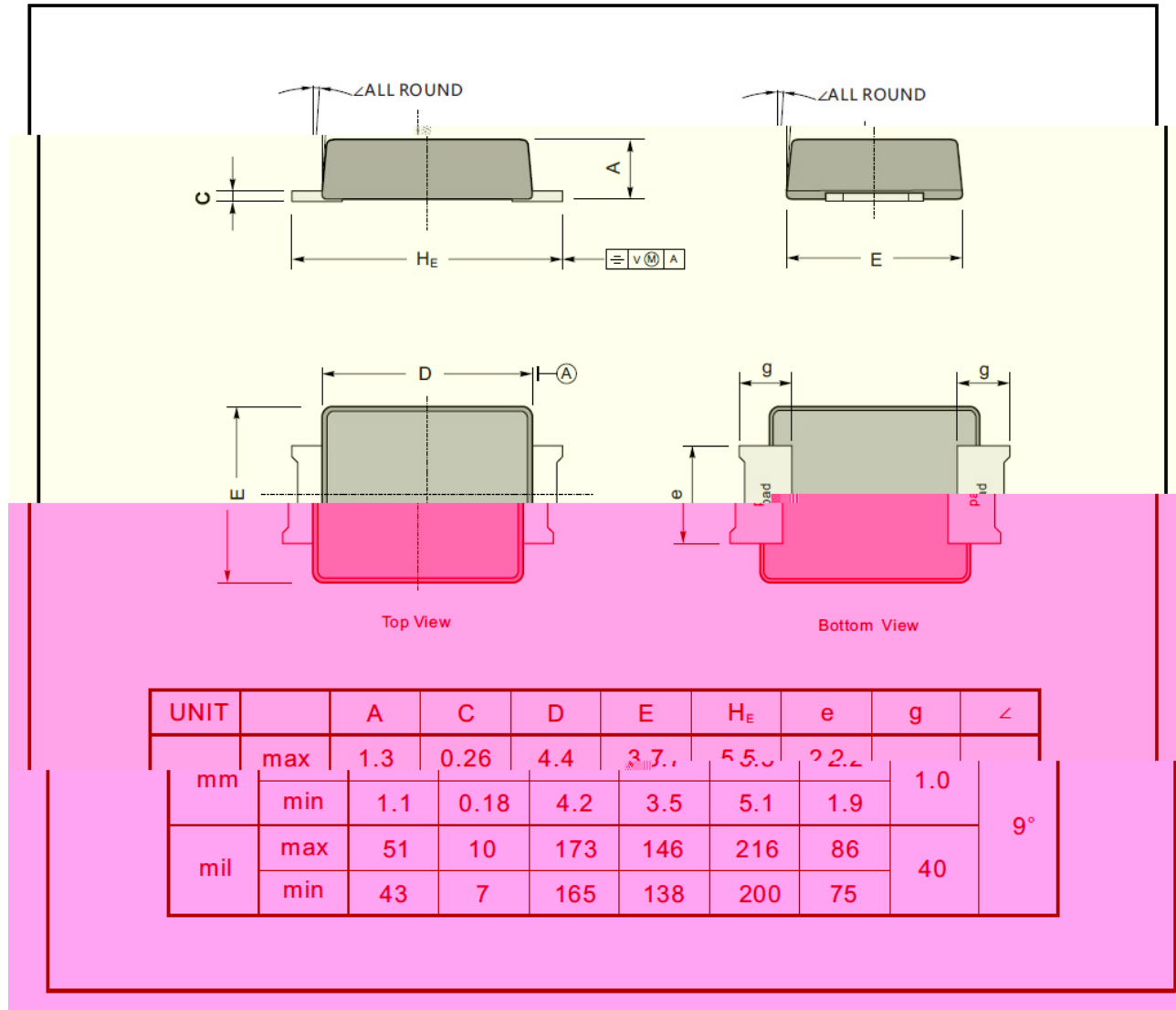
See Marking Instructions

Rev.E May.-2019

Parameter	Symbol	Rating							Unit
		ES1ABF	ES1BBF	ES1CBF	ES1DBF	ES1EBF	ES1GBF	ES1JBF	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at $T_L = 100$	$I_{F AV}$	1.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35							A
Typical Junction Capacitance at $V_R = 4V$, $f = 1MHz$	C_j	10							pF
Typical Thermal Resistance ¹	$R_{\theta JA}$								

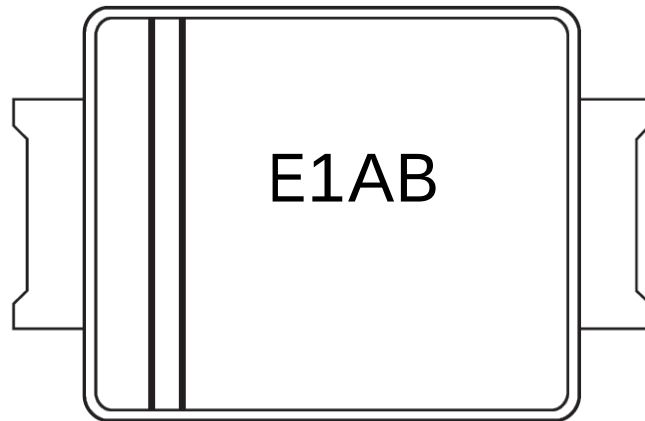


SMBF



Marking

Type number		Marking code
BF	E1BA	ES1B
BF	E1BB	ES1B
BF	E1CB	ES1C
BF	E1DB	ES1D
BF	E1EB	ES1E
BF	E1GB	ES1G
BF	E1JB	ES1J



E1AB

1 *

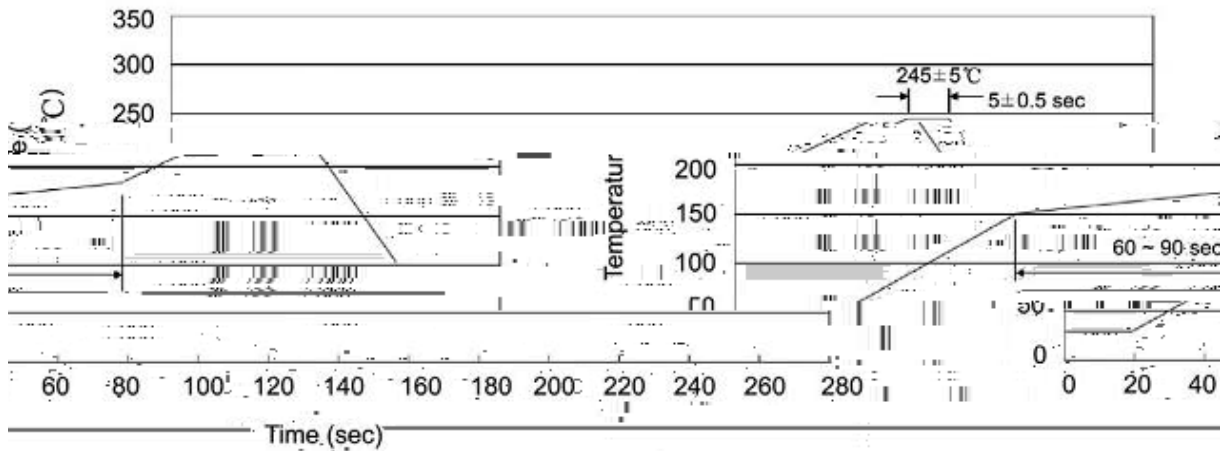
3 *

Note:

E1AB Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No
Code

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;
- 2

245±5

5±0.5sec;
- 3

2 10

/sec.
- 1.Preheating:150~180

, Time:60~90sec.
- 2.Peak Temp.:245±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

260±5

10±1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱